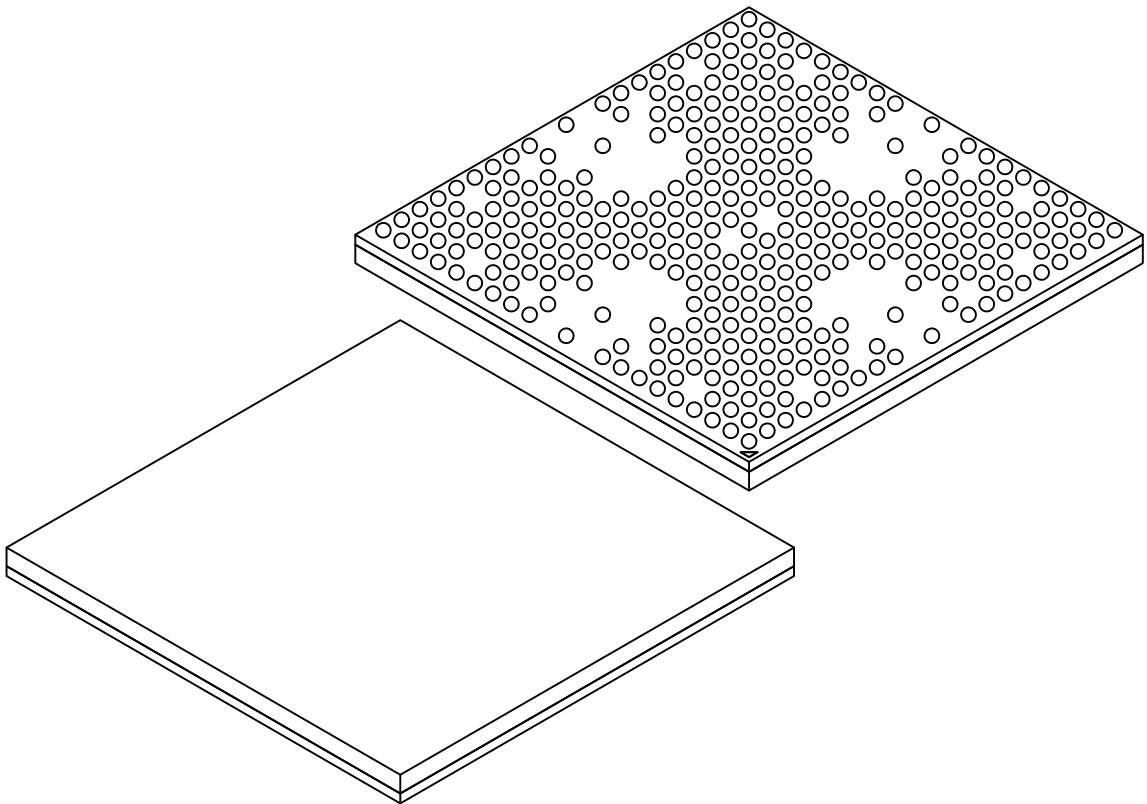


343-Ball Plastic Thin Fine Pitch Ball Grid Array (4HB) - 14x14x1.2 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		343		
Pitch	e		0.65 BSC		
Overall Height	A	-	-	-	1.20
Standoff	A1	0.22	0.27	0.32	
Substrate Thickness	S		0.26 REF		
Mold Cap Height	M		0.53 REF		
Overall Length	D		14.00 BSC		
Overall Width	E		14.00 BSC		
Ball Diameter	b	0.32	0.35	0.42	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.